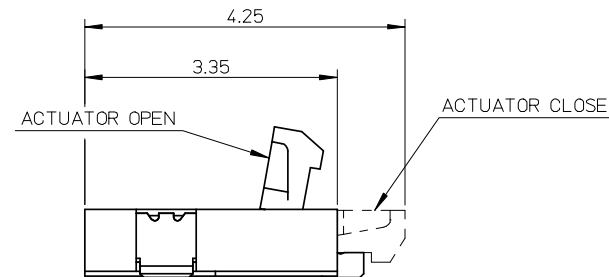
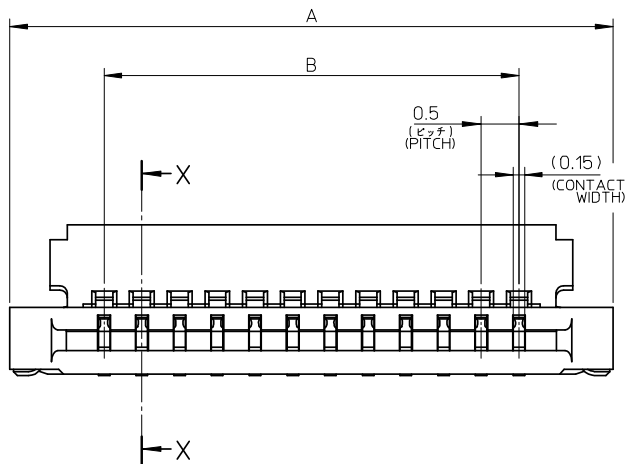
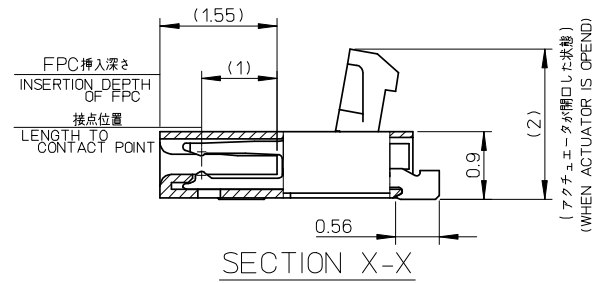
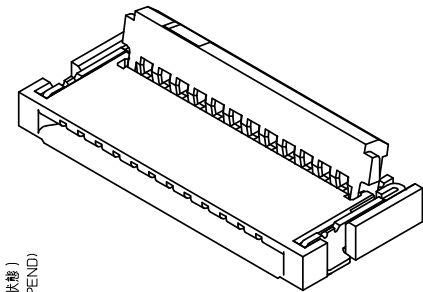
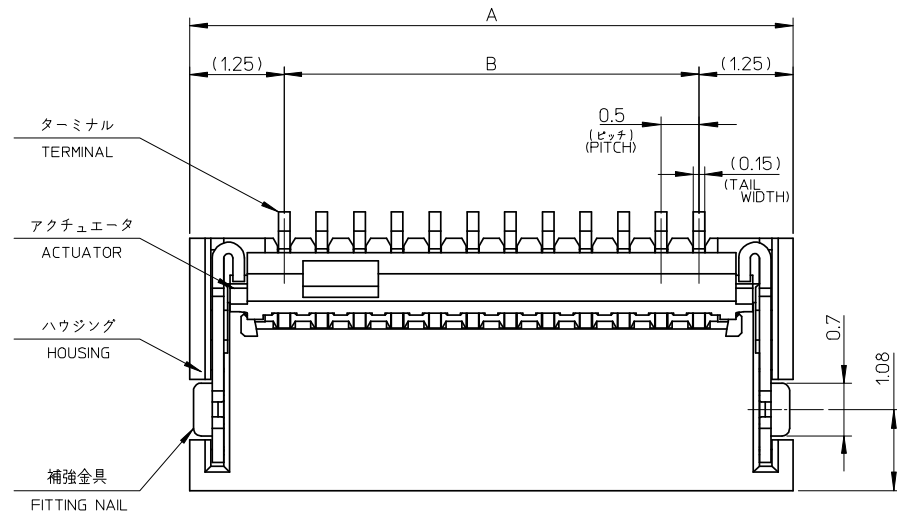
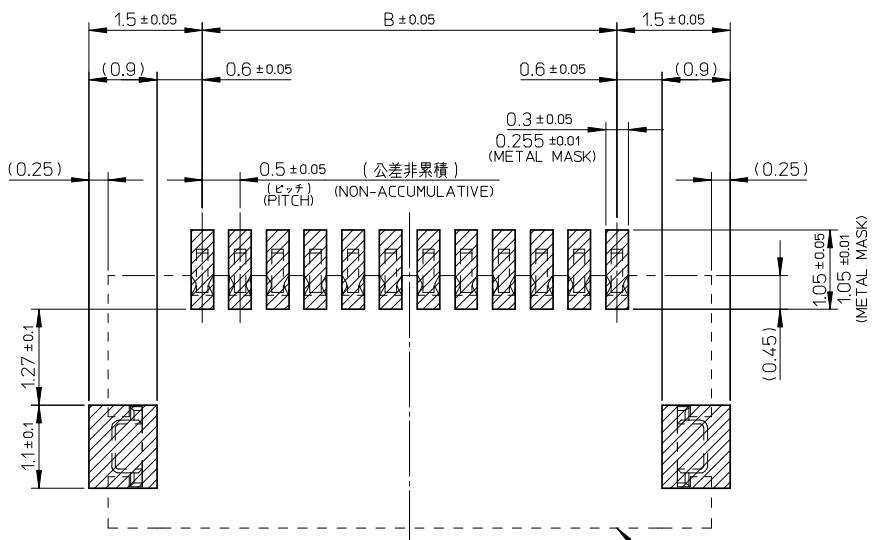


10 9 8 7 6 5 4 3 2 1



25.5	24.5	27	502118-5090	502118-5011	50
C	B	A	EMBOSSED PACKAGING	MATERIAL NO.	CIRCUITS
			ORDER NO.		

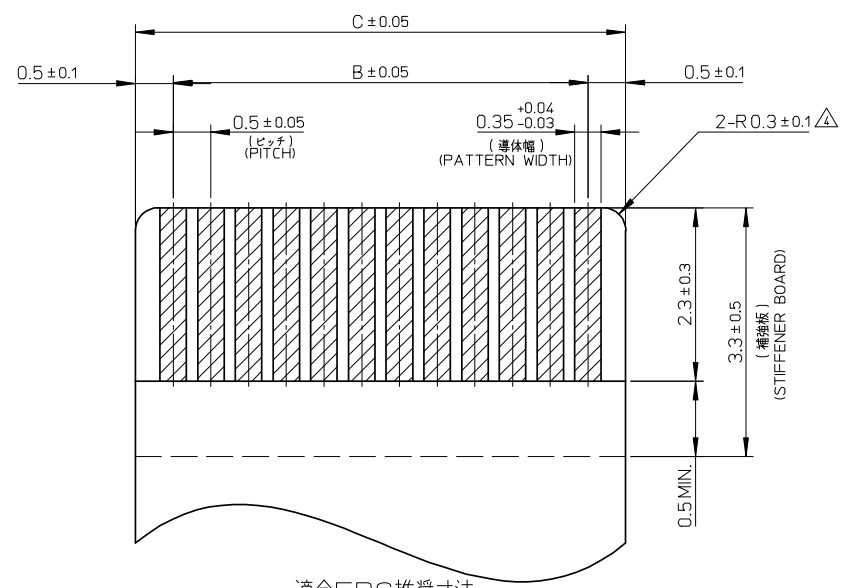
RELEASED EC NO: J2009-0131 DRWN:HONO01 2008/07/18 CHKD:HSHIMOYAMA 2008/07/18 APPR:HHIRATA 2008/07/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE //	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY HONO	DATE 2008/07/15	TITLE 0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT		
	10 OVER 30 UNDER	±0.25	CHECKED BY HSHIMOYAMA	DATE 2008/07/15	MOLEX INCORPORATED		
	30 OVER	±0.3	APPROVED BY HHIRATA	DATE 2008/07/15	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-502118-001	SHEET NO. 1 OF 2
	ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		



参考基板レイアウト
P.C BOARD PATTERN
DIMENSION (REF.)
(マウント面)
(MOUNTING SIDE)

コネクタ位置
CONNECTOR POSITION

推奨メタルマスク厚さ: 0.12mm
RECOMMENDED METAL MASK THICKNESS: 0.12mm



適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.20±0.03)
(THICKNESS: 0.20±0.03)

注記 NOTE

1. 使用材料 MATERIAL

- ハウジング : ポリアミド樹脂, 色: ベージュ
HOUSING : GLASS FILLED, UL94V-0
POLYAMIDE, COLOR: BEIGE
GLASS FILLED, UL94V-0
- アクチュエータ : ポリアミド樹脂, 色: 茶
ACTUATOR : GLASS FILLED, UL94V-0
POLYAMIDE, COLOR: BROWN
GLASS FILLED, UL94V-0
- ターミナル : りん青銅 (t=0.15)
TERMINAL : PHOSPHOR BRONZE (t=0.15)
- 補強金具 : りん青銅 (t=0.15)
FITTING NAIL : PHOSPHOR BRONZE (t=0.15)

△ R0.3はFPC導体部にかからないこと。
R0.3 MUST NOT BE OVERLAPPED
TO PATTERN OF FPC.

5. ELV及びRoHS適合品
ELV AND RoHS COMPLIANT.

6. 基板実装前にアクチュエータを操作しないで下さい。
必ず基板に実装し、FPCを挿入してから
アクチュエータを操作して下さい。
PLEASE DO NOT OPERATE THE ACTUATOR
BEFORE MOUNTING.
PLEASE OPERATE THE ACTUATOR AFTER MOUNTING ON
THE SUBSTRATE, AND MATING FPC.

2. めっき仕様 PLATING

- ターミナル
TERMINAL
ニッケル下地、部分金めっき (テールおよびコンタクト部)
SEPARATED GOLD TAIL AND CONTACT)
OVER NICKEL PLATING.
- 補強金具
FITTING NAIL
ニッケル下地錫めっき
TIN OVER NICKEL PLATING.

3. 端子、補強金具の平坦度は0.1以下とする。
COPLANARITY OF SOLDER TAIL AND FITTING NAIL : 0.1 MAX.

FPCについて
ABOUT FPC

抜き方向は、導体側から補強板を推奨します。
補強板材質は、ポリイミドを推奨します。
接着剤は熱硬化接着剤を推奨します。
なお、接着剤の接点部への付着は導通不良の
原因となりますので染み出しの無いよう、お願いします。

RECOMMENDED PUNCHER DIRECTION :
FROM CONDUCTOR SIDE TO STIFFENER BOARD SIDE.
RECOMMENDED MATERIAL :
STIFFENER BOARD : POLYIMIDE
BONDING AGENT : THERMOSETTING AGENT
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND
BECAUSE THERE IS A POSSIBILITY
THAT THE EXTRA ADHESIVE CAUSES THE DEFECT
IN ELECTRICAL CONTINUITY.

RELEASED EC NO: J2009-0131 DRWN: HON001 2008/07/18 CHKD: HSHIMOYAMA 2008/07/18 APPR: HHIRATA 2008/07/18	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
				MM ONLY		≠	METRIC		
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE			
		10 OVER 30 UNDER	±0.25	HONO	2008/07/15	0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT			
		30 OVER	±0.3	CHECKED BY	DATE				
		ANGULAR ±1 °		HSHIMOYAMA	2008/07/15				
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY	DATE	MOLEX INCORPORATED			
				HHIRATA	2008/07/15	MOLEX INCORPORATED			
				MATERIAL NO.		DOCUMENT NO.			
				SEE CHART		SD-502118-001		SHEET NO. 2 OF 2	
				THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

F

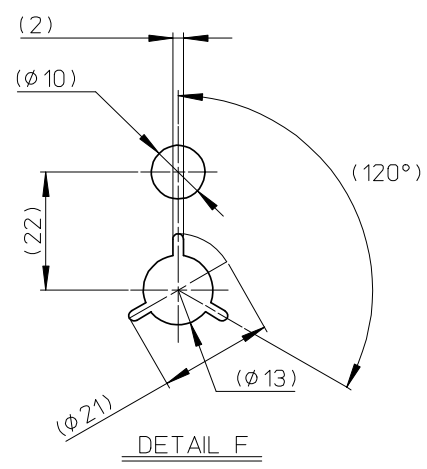
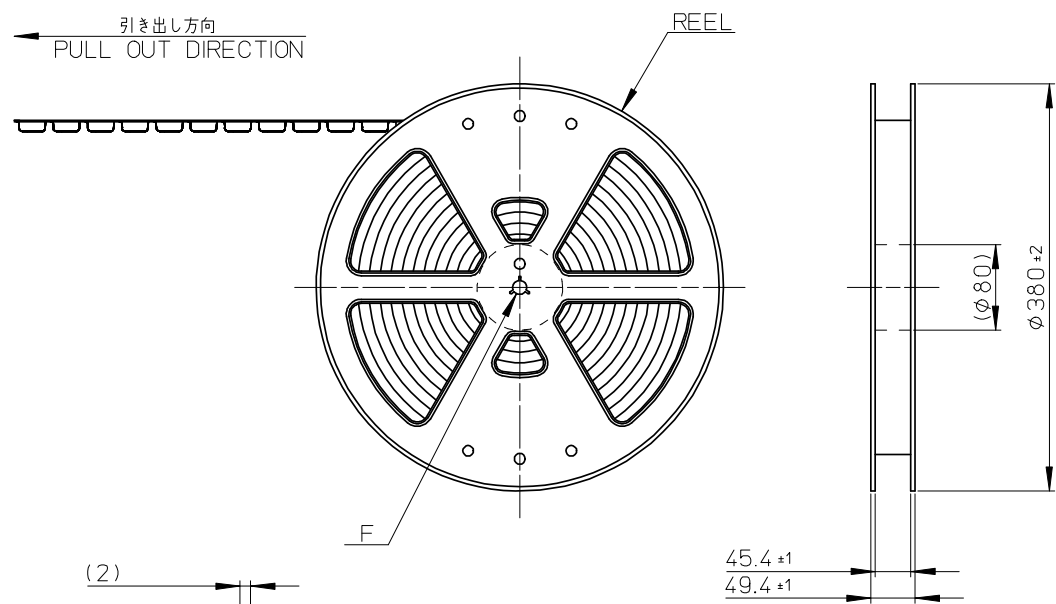
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D

C

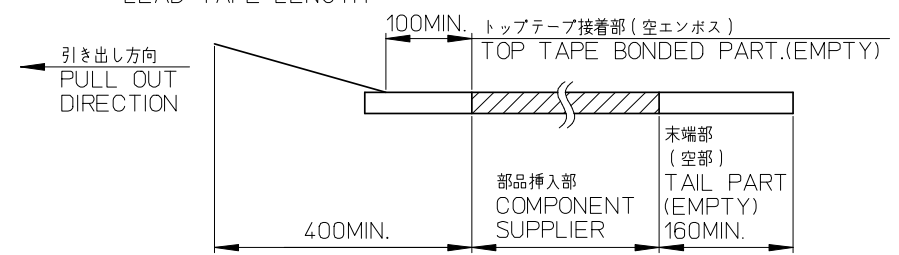
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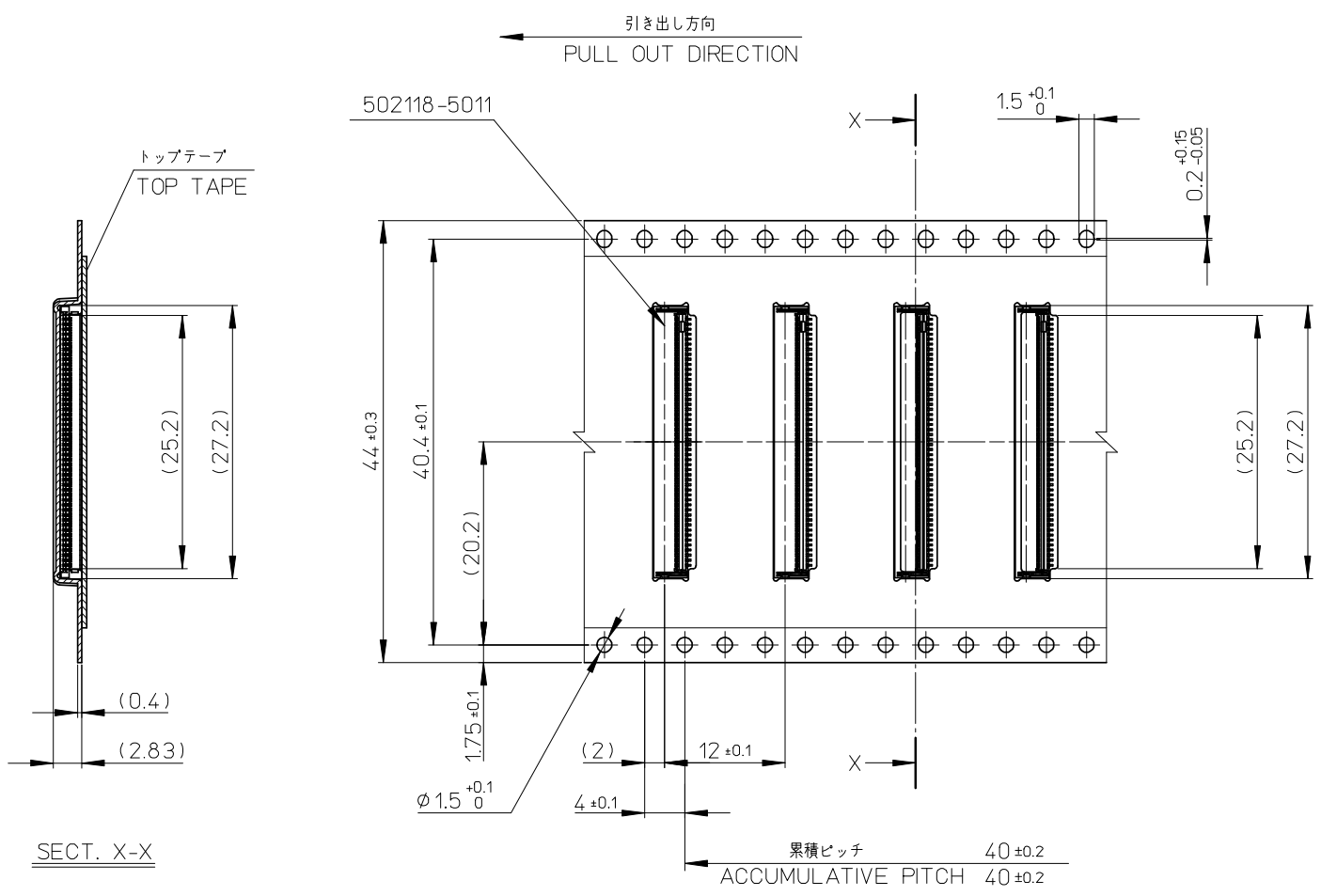
NOTES

- 製品詳細寸法については製品単体図面を参照下さい。
RE DETAILED DIMENSION, SEE PRODUCT DRAWING.
- 梱包数量: 2500個/リール
NUMBER OF CONNECTORS 2500PCS/REEL
- リードテープ長さ
LEAD TAPE LENGTH



- 材料
MATERIAL
キャリアテープ(CARRIRE TAPE): ポリスチレン (POLYSTYRENE)
トップテープ(TOP TAPE): PET, PE, PEF
リール(REEL): ポリスチレン (PS) <リサイクル材を含む>
POLYSTYRENE(PS) <RECYCLE MATERIAL CONTAILED>
- ELV及びRoHS適合品
ELV AND RoHS COMPLIANT.

RELEASED EC NO: J2009-0131 2008/07/18 DRWN:HONO01 CH'KD:SHIMOYAMA APPR:HHIRATA 2008/07/18 2008/07/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
	10 UNDER	±0.2	DRAWN BY HONO	DATE 2008/7/15	TITLE 0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT EMBSTP PKG			
	10 OVER 30 UNDER	±0.25	CHECKED BY HSHIMOYAMA	DATE 2008/7/15				
	30 OVER	±0.3	APPROVED BY HHIRATA	DATE 2008/7/15	MOLEX INCORPORATED			
	ANGULAR	±1 °	MATERIAL NO. SEE CHART	DOCUMENT NO. SD-502118-002				
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				



502118-5090	50
MATERIAL NO.	CIRCUITS

RELEASED EC NO: J2009-0131 DRWN: HON001 CHKD: HS IMOYAMA APPR: HIRATA	2008/07/18 2008/07/18 2008/07/18	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY HONO	DATE 2008/7/15	TITLE 0.5 FPC CONN BACK FLIP H=0.9 UPR/BTM CONT EMBSTP PKG				
		10 OVER 30 UNDER	± 0.25	CHECKED BY HSHIMOYAMA	DATE 2008/7/15					
		30 OVER	± 0.3	APPROVED BY HIRATA	DATE 2008/7/15	MOLEX INCORPORATED				
ANGULAR ±1 °		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-502118-002	SHEET NO. 2 OF 2					
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								